



Material Composition Declaration

EPC2203

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/1/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	1.2734	88.7933	91.1661	887933
	Silicon oxide	7631-86-9	0.0050	0.3509		3509
	Silicon nitride	12033-89-5	0.0017	0.1178		1178
	Gallium nitride	25617-97-4	0.0060	0.4175		4175
	Aluminum	7429-90-5	0.0095	0.6612		6612
	Aluminum nitride	24304-00-5	0.0014	0.1008		1008
	Titanium	7440-32-6	0.0002	0.0146		146
	Titanium nitride	25583-20-4	0.0008	0.0589		589
	Copper	7440-50-8	0.0003	0.0220		220
	Tungsten	7440-33-7	0.0003	0.0234		234
	Polyimide		0.0087	0.6057		6057
Under Bump Metal	Titanium	7440-32-6	0.0001	0.0056	0.1458	56
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0020	0.1402		1402
Solder Bar	Tin	7440-31-5	0.1190	8.2971	8.6881	82971
	Silver	7440-22-4	0.0050	0.3475		3475
	Copper	7440-50-8	0.0006	0.0434		434
Sum in total:			1.4341	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.